



Material Content Data Sheet



Sales Product Name		TLE5009 E1010		Issued		25. September 2017		
MA#		MA000983846						
Package		PG-DSO-8-16		Weight*		83.34 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.725	2.07	2.07	20705	20705
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.717	0.86		8606	
wire	non noble metal	copper	7440-50-8	29.121	34.94	35.85	349431	358575
	noble metal	gold	7440-57-5	0.383	0.46	0.46	4601	4601
	encapsulation	organic material	carbon black	1333-86-4	0.098	0.12		1171
plastics		epoxy resin	-	4.490	5.39		53879	
	inorganic material	silicondioxide	60676-86-0	44.218	53.06	58.57	530588	585638
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9765	9765
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7803	7803
glue	plastics	acrylic resin	-	0.237	0.28		2841	
	noble metal	silver	7440-22-4	0.839	1.01	1.29	10072	12913
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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